

PCB Manufacturing Notes

General Info

Board dimensions – 34mm x 30mm  
Number of layers – 2  
Smallest hole – 0.5mm  
Number of holes – Approx 70  
Minimum Track & Gap – 0.15mm  
RoHS/Lead Free – Yes  
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion silver or immersion gold.

B.) Soldermask

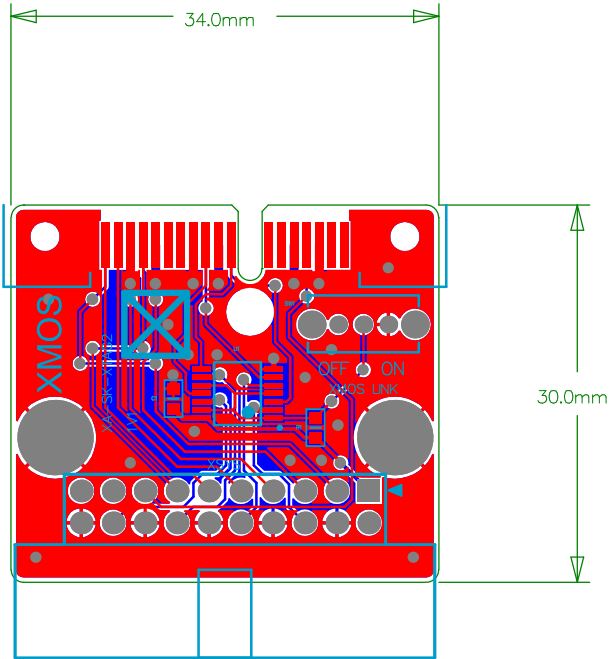
Liquid photo imageable soldermask (green). Pads have not been oversized.  
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.  
Hole size is finished size.



XMOS LTD = XPCB-058 = 1V1 = 31 JULY 2012  
LAYER – 01 (TOP)  
LAYER – 02 (BOTTOM)



Project Name  
XPCB-058 (XA-SK-XTAG2)

Sheet	Date	Revision
A4	JULY 31 2012	1V1

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B.) Soldermask

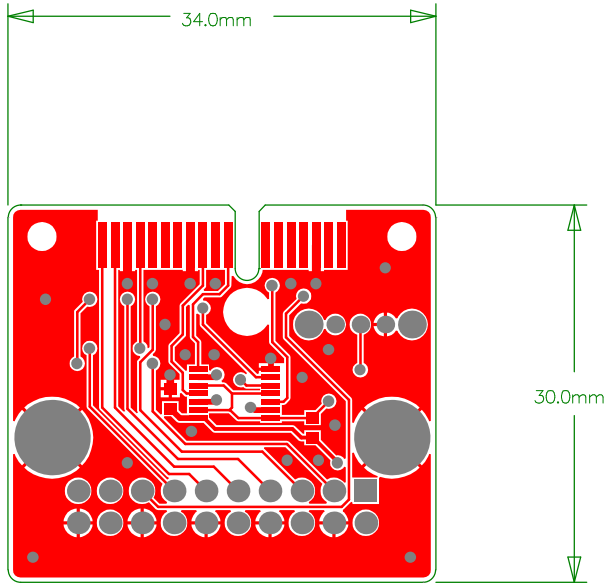
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LAYER – FABRICATION INSTRUCTIONS



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Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion silver or immersion gold.

B.) Soldermask

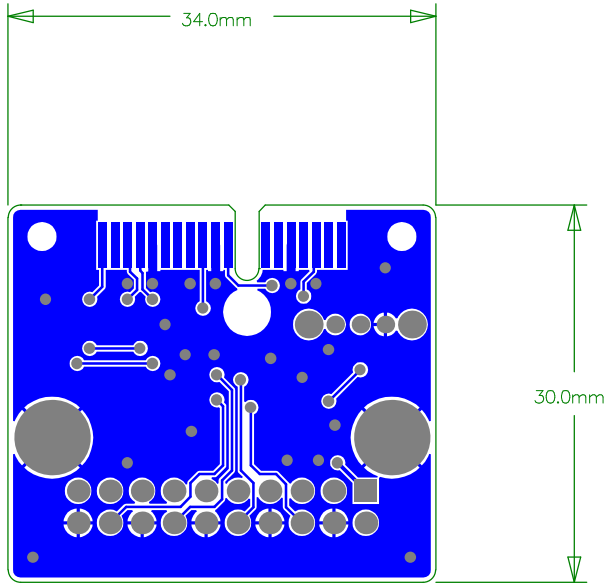
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FABRICATOR INSTRUCTIONS (BOTTOM)



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Not required.

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Finish

A.) Conductive finish

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### B.) Soldermask

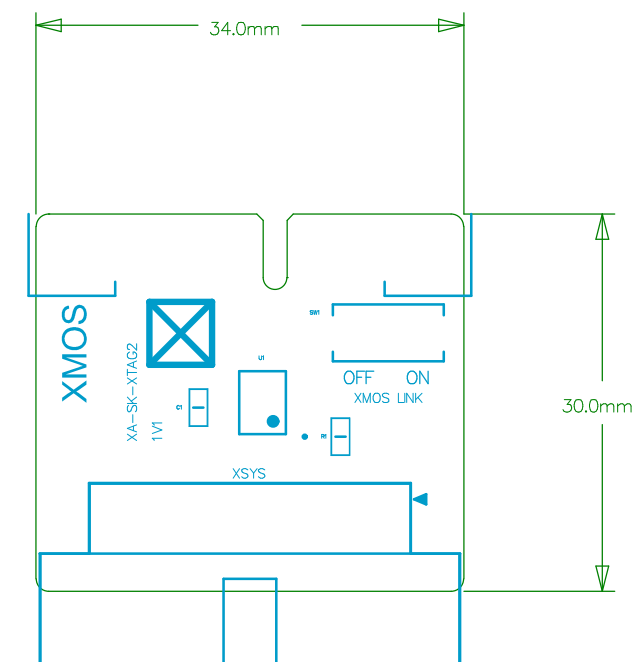
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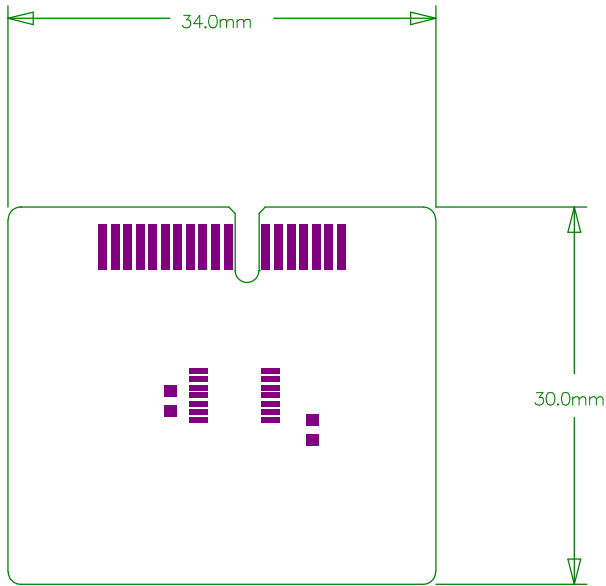
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SOLDERMASK INSTRUCTIONS



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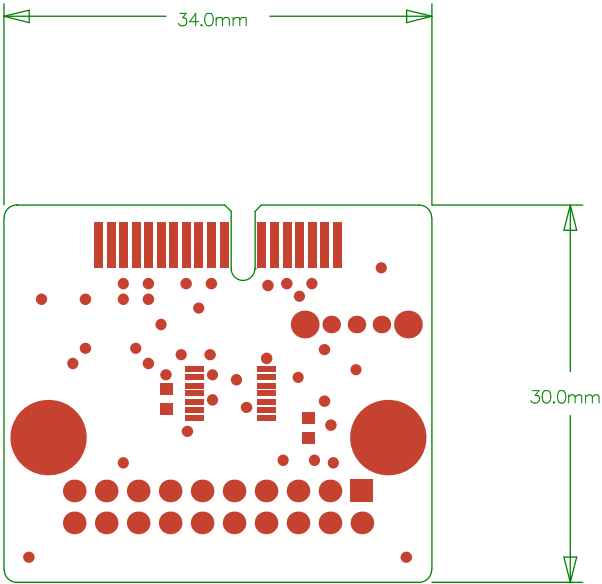
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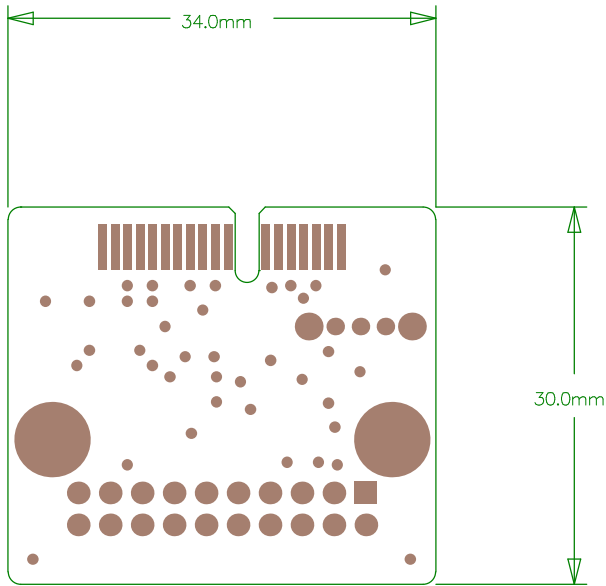
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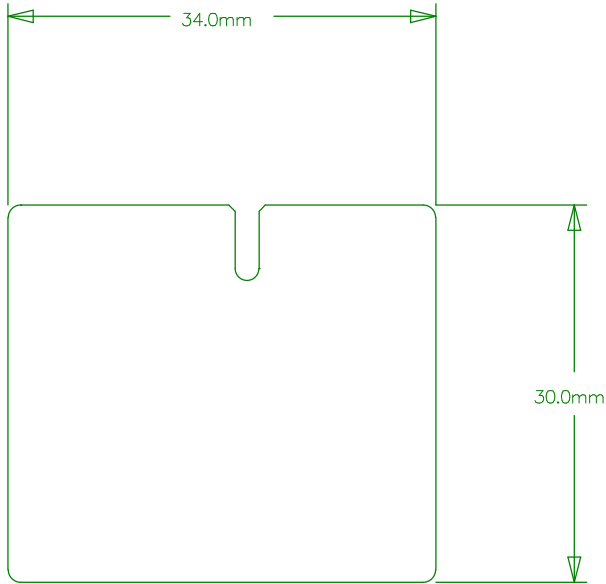
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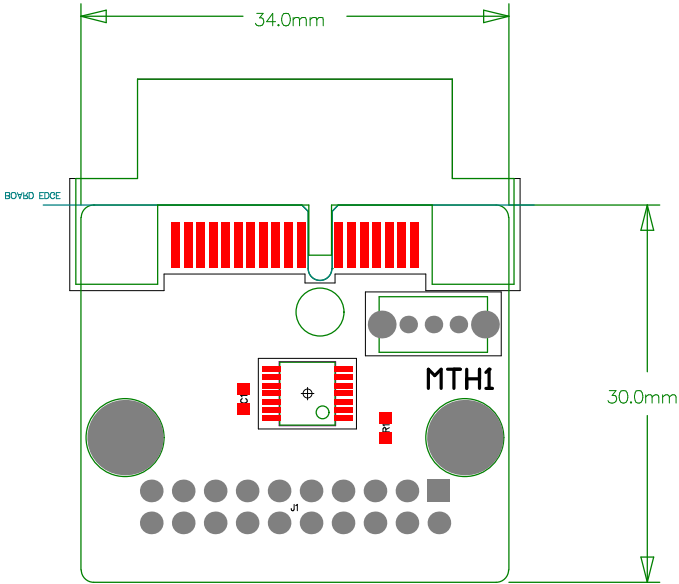
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ASSEMBLY DRAWING BOTTOM



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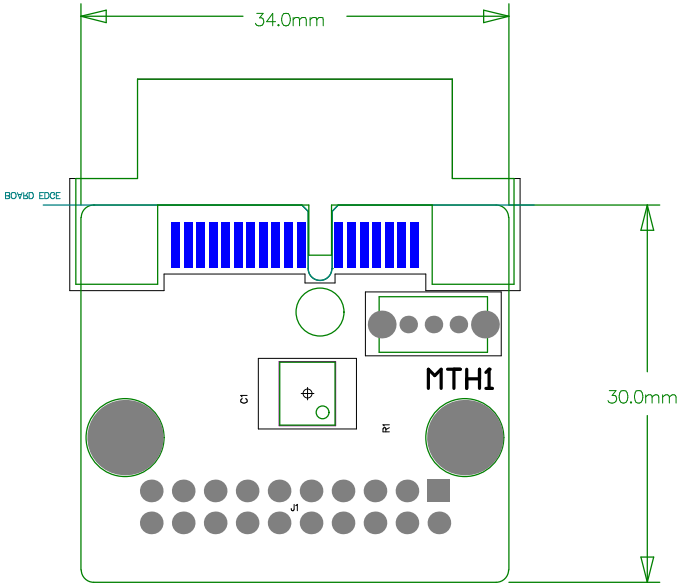
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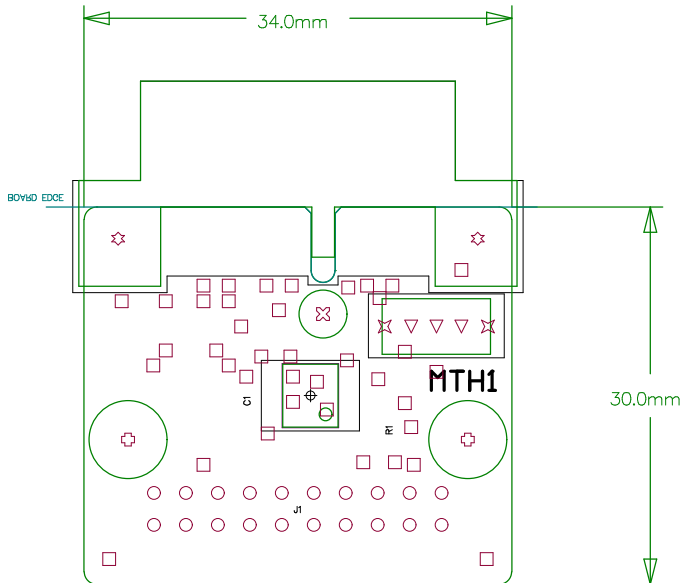
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Symbol	Hit Count	Tool Size	Plated	Hole Type
□	39	0.5mm (19.685mil)	PTH	Round
▽	3	0.8mm (31.496mil)	PTH	Round
○	20	1mm (39.37mil)	PTH	Round
✕	2	1.5mm (59.055mil)	PTH	Round
☆	2	2mm (78.74mil)	NPTH	Round
⊗	1	2.8mm (110.236mil)	NPTH	Round
⊕	2	3.2mm (125.984mil)	PTH	Round
	69 Total			

Drill Drawing.

**XMOS®**

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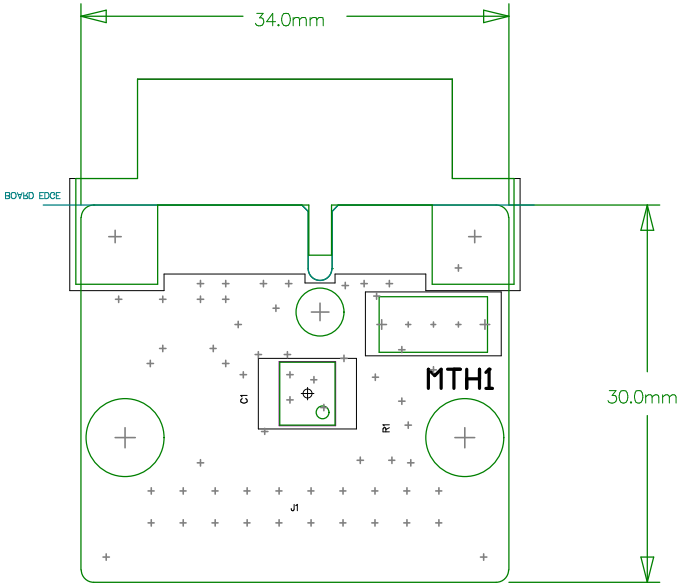
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# BOM

sliceKIT XTAG2 Adapter

Source Data From:

XPCB-058 XA-SK-XTAG2.PrjPCB

Project:

XPCB-058 XA-SK-XTAG2.PrjPCB

Variant:

None



Report Date:

04/12/2012

16:39:57

Print Date:

04-Dec-12

4:40:00 PM

#	LibRef	Designator	Description	Quantity
1	E-01-0002	R1	RES 10k 0603 1%	1
2	E-02-0017	C1	MLCC 100nF 0603 X7R 16V	1
3	E-04-0022	J1	IDC Boxed Header, Right Angle, PCB Mount, Polarised, 20 Way, 2x10, 0.1" Pitch	1
4	E-04-0067	J2	PCle End Fire Socket, x1, 36 Pin, SMD	1
5	E-13-0101	U1	Quad Bus Switch, CBT Series, TSSOP14	1
6	E-16-0006	SW1	Miniature Slide Sw itch, SPDT, Vertical, THT	1
7	P-01-0011	PROD1, PROD2	Feet, Nylon, M3, 6mm Standoff	2
Approved			Notes	8